



APPLICATION DATA SHEET

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Title of Invention	EXTRUSION-FREE WET CLEANING PROCESS FOR COPPER-DUAL DAMASCENE STRUCTURES		
Application Type : regular, utility Attorney Docket Number : NAUP0374USA3			
Correspondence address: Customer Number: 027765			
			
Continuing Data: This is a Continuation of US application number 09/682,054, filed 2001-07-16 , now PENDING.			
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